

US Patent & Trademark Office

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United States Patent Application Publication

20250268046

Kind Code

A1

Publication Date

August 21, 2025

Inventor(s)

CHOI; Min Hee et al.

DISPLAY DEVICE

Abstract

A display device includes a light emitting diode electrically connected between a driving voltage line and a common voltage line; a driving transistor electrically connected between the driving voltage line and the light emitting diode; a second transistor electrically connected between a first electrode of the driving transistor electrically connected to the driving voltage line and a data line; a first scan line electrically connected to a gate electrode of the second transistor; a third transistor electrically connected between a second electrode of the driving transistor electrically connected to the light emitting diode and a gate electrode of the driving transistor; and a connection electrode that connects the gate electrode of the driving transistor and the third transistor, wherein at least a part of a contact portion where the connection electrode contacts the third transistor does not overlap the first scan line.

Inventors: CHOI; Min Hee (Hwaseong-si, KR), LEE; Ji-Eun (Seoul, KR), JEONG; Jin Tae (Suwon-si, KR), JOO; Yun Sik (Goyang-si, KR)

Applicant: Samsung Display Co., LTD. (Yongin-si, KR)

Family ID: 1000008578410

Assignee: Samsung Display Co., LTD. (Yongin-si, KR)

Appl. No.: 19/201266

Filed: May 07, 2025

Foreign Application Priority Data

KR 10-2020-0066617

Jun. 02, 2020

Related U.S. Application Data

parent US continuation 18429598 20240201 parent-grant-document US 12310205 child US 19201266

parent US continuation 17941207 20220909 parent-grant-document US 11963417 child US

Publication Classification

Int. Cl.: **H10K59/131** (20230101); **G09G3/3233** (20160101); **G09G3/3258** (20160101); **G09G3/36** (20060101)

U.S. Cl.:

CPC **H10K59/1315** (20230201); **G09G3/3258** (20130101); G09G3/3233 (20130101); G09G3/3659 (20130101); G09G2300/0426 (20130101); G09G2300/043 (20130101); G09G2300/0809 (20130101); G09G2300/0819 (20130101); G09G2300/0842 (20130101); G09G2310/0202 (20130101); G09G2310/0254 (20130101)

Background/Summary

CROSS-REFERENCE TO RELATED APPLICATIONS [0001] This is a continuation application of U.S. patent application Ser. No. 18/429,598, filed Feb. 1, 2024 (now pending), the disclosure of which is incorporated herein by reference in its entirety. U.S. patent application Ser. No. 18/429,598 is a continuation application of U.S. patent application Ser. No. 17/941,207, filed Sep. 9, 2022, now U.S. Pat. No. 11,963,417, which issued Apr. 16, 2024, the disclosure of which is incorporated herein by reference in its entirety. U.S. patent application Ser. No. 17/941,207 is a continuation application of U.S. patent application Ser. No. 17/245,576, filed Apr. 30, 2021, now U.S. Pat. No. 11,444,147, which issued Sep. 13, 2022, the disclosure of which is incorporated herein by reference in its entirety. U.S. patent application Ser. No. 17/245,576 claims priority to and the benefits of Korean Patent Application No. 10-2020-0066617 under 35 U.S.C. § 119, filed Jun. 2, 2020, in the Korean Intellectual Property Office, the entire contents of which are incorporated herein by reference.

BACKGROUND

1. Technical Field

[0002] The disclosure relates to a display device.

2. Description of the Related Art

[0003] An organic light emitting device includes an organic emission layer disposed between two electrodes, and electrons injected from one electrode are combined with holes injected from the other electrode in an organic emission layer to form excitons. The excitons output energy and emit light when they transition from an excited state to a ground state.

[0004] The organic light emitting device includes multiple pixels, each of which includes an organic light emitting diode (a self-luminous device), and multiple transistors, and at least one capacitor for driving the organic light emitting diode. The transistors include a switching transistor and a driving transistor.

[0005] Each pixel may also include a transistor for transmitting a compensation voltage. In case that the compensation voltage transfer route overlaps other wires, resistance may increase, and the compensation voltage may not be properly transmitted. This may cause horizontal line defects e.g., horizontal stains.

[0006] The information disclosed in this Background section is provided to enhance understanding of the background of the described technology. It may contain information that is not part of the

prior art that is already known to a person of ordinary skill in the art.

SUMMARY

[0007] The disclosure has been made in an effort to provide a display device for smoothly transmitting a compensation voltage by reducing a resistance of a compensation voltage transfer route.

[0008] The described technology has been made in another effort to provide a display device for reducing horizontal line defects.

[0009] An embodiment provides a display device including a light emitting diode electrically connected between a driving voltage line that applies a driving voltage and a common voltage line that applies a common voltage; a driving transistor electrically connected between the driving voltage line and the light emitting diode; a second transistor electrically connected between a first electrode of the driving transistor electrically connected to the driving voltage line and a data line that applies a data voltage; a first scan line electrically connected to a gate electrode of the second transistor; a third transistor electrically connected between a second electrode of the driving transistor electrically connected to the light emitting diode and a gate electrode of the driving transistor; a connection electrode that electrically connects the gate electrode of the driving transistor and the third transistor; and a contact portion where the connection electrode electrically contacts the third transistor. At least a part of the contact portion may not overlap the first scan line.

[0010] In an embodiment, the contact portion may not overlap the first scan line.

[0011] In an embodiment, the third transistor may include a first electrode electrically connected to a first electrode of the driving transistor; a second electrode electrically connected to the connection electrode; a channel disposed between the first electrode and the second electrode; and a gate electrode overlapping the channel. The second electrode of the third transistor may overlap the connection electrode.

[0012] In an embodiment, the display device may further include an insulating layer disposed between the second electrode of the third transistor and the connection electrode. The insulating layer may include an opening overlapping the second electrode of the third transistor and the connection electrode, the second electrode of the third transistor may be electrically connected to the connection electrode through the opening, and the opening may not overlap the first scan line.

[0013] In an embodiment, the contact portion may be disposed in the opening.

[0014] In an embodiment, the display device may further include a second scan line electrically connected to the gate electrode of the third transistor. The opening may be disposed between the first scan line and the second scan line in a plan view.

[0015] In an embodiment, a side edge of the opening may correspond to a side edge of the first scan line.

[0016] In an embodiment, the connection electrode may overlap the first scan line.

[0017] In an embodiment, the opening may be separated from the first scan line.

[0018] In an embodiment, the connection electrode may not overlap the first scan line.

[0019] In an embodiment, the driving transistor and the second transistor may include polycrystalline semiconductors and may be p-type transistors, and the third transistor may include an oxide semiconductor and may be an n-type transistor.

[0020] In an embodiment, voltages having opposite polarities may be applied to the first scan line and the second scan line, respectively, at a same time.

[0021] In an embodiment, the display device may further include a boost capacitor electrically connected between the gate electrode of the second transistor and the second electrode of the third transistor. The contact portion may not overlap the boost capacitor.

[0022] In an embodiment, the contact portion may include a first part that overlaps the first scan line, a second part that does not overlap the first scan line, and the second part is a remaining area of the contact portion other than the first part.

[0023] In an embodiment, the third transistor may include a first electrode electrically connected to

the first electrode of the driving transistor; a second electrode electrically connected to the connection electrode; a channel disposed between the first electrode and the second electrode; and a gate electrode overlapping the channel. The second electrode of the third transistor may overlap the connection electrode.

[0024] In an embodiment, the display device may further include an insulating layer disposed between the second electrode of the third transistor and the connection electrode. The insulating layer may include an opening overlapping the second electrode of the third transistor and the connection electrode, the second electrode of the third transistor may be electrically connected to the connection electrode through the opening, and the opening may include a first part that overlaps the first scan line, and a second part that does not overlap the first scan line, the second part being a remaining portion of the opening other than the first part.

[0025] In an embodiment, the contact portion may be disposed in the opening.

[0026] In an aspect, an embodiment provides a display device including a driving transistor including a first electrode, a channel, and a second electrode disposed on a substrate, the driving transistor including a polycrystalline semiconductor; a first gate insulating layer disposed on the first electrode, the channel, and the second electrode of the driving transistor; a gate electrode of the driving transistor disposed on the first gate insulating layer and overlapping the channel of the driving transistor; a first scan line disposed on the first gate insulating layer; a second gate insulating layer disposed on the gate electrode of the driving transistor and the first scan line; a lower second scan line disposed on the second gate insulating layer; a first interlayer insulating layer disposed on the lower second scan line; a third transistor including a first electrode, a channel, and a second electrode, the third transistor being disposed on the first interlayer insulating layer and including an oxide semiconductor; a third gate insulating layer disposed on the first electrode, the channel, and the second electrode of the third transistor; a gate electrode of the third transistor disposed on the third gate insulating layer; a second interlayer insulating layer disposed on the gate electrode of the third transistor; a connection electrode disposed on the second interlayer insulating layer and electrically connecting the gate electrode of the driving transistor and the second electrode of the third transistor; and a contact portion where the connection electrode electrically contacts the second electrode of the third transistor. At least a part of the contact portion may not overlap the lower second scan line.

[0027] In an embodiment, the second interlayer insulating layer and the third gate insulating layer may include an opening overlapping the connection electrode and the second electrode of the third transistor, the contact portion may be disposed in the opening, and at least a part of the opening may not overlap the first scan line.

[0028] In an embodiment, the display device may further include an upper second scan line, the upper second scan line and the gate electrode of the third transistor being integral with each other. The opening may be disposed between the first scan line and the upper second scan line in a plan view, and the opening may not overlap the upper second scan line.

[0029] In an embodiment, the display device may further include a second transistor electrically connected to the first scan line, wherein the driving transistor and the second transistor may include polycrystalline semiconductors and may be p-type transistors, the third transistor may include an oxide semiconductor and may be an n-type transistor, and voltages having opposite polarities may be applied to the first scan line and the second scan line, respectively, at a same time.

[0030] In an embodiment, The display device may further include a first boost electrode, the first boost electrode and the first scan line being integral with each other, a second boost electrode, the second boost electrode and the second electrode of the third transistor being integral with each other, wherein the first boost electrode may overlap the second boost electrode with the second gate insulating layer and the first interlayer insulating layer being disposed between the first boost electrode and the second boost electrode to form a boost capacitor, and at least a part of the contact portion may not overlap the boost capacitor.

[0031] According to embodiments, the compensation voltage may be smoothly transmitted by reducing resistance on the compensation voltage transfer route CTR, thereby reducing the horizontal line defects on a display device.

Description

BRIEF DESCRIPTION OF THE DRAWINGS

[0032] An additional appreciation according to the embodiments of the disclosure will become more apparent by describing in detail some embodiments thereof with reference to the accompanying drawings, wherein:

[0033] FIG. 1 shows a schematic circuit diagram of a display device according to an embodiment.

[0034] FIG. 2 shows a schematic top plan view of a display device according to an embodiment.

[0035] FIG. 3 shows a schematic cross-sectional view with respect to line III-III of FIG. 2.

[0036] FIG. 4 shows a schematic cross-sectional view with respect to line IV-IV of FIG. 2.

[0037] FIG. 5 to FIG. 10 show schematic sequential plan views illustrating manufacturing steps of a display device according to an embodiment.

[0038] FIG. 11 shows a schematic plan view of part of a display device according to an embodiment.

[0039] FIG. 12 shows a schematic plan view of a display device according to a comparative example.

[0040] FIG. 13 shows a schematic cross-sectional view with respect to line XIII-XIII of FIG. 12.

[0041] FIG. 14 shows a schematic plan view of a display device according to an embodiment.

[0042] FIG. 15 shows a schematic cross-sectional view with respect to line XV-XV of FIG. 14.

[0043] FIG. 16 shows a schematic plan view of part of a display device according to an embodiment.

[0044] FIG. 17 shows a schematic plan view of a display device according to an embodiment.

[0045] FIG. 18 shows a schematic cross-sectional view with respect to line XVIII-XVIII of FIG. 17.

[0046] FIG. 19 shows a schematic plan view of part of a display device according to an embodiment.

DETAILED DESCRIPTION OF THE EMBODIMENTS

[0047] Since the disclosure may have diverse modified embodiments, some embodiments are illustrated in the drawings and are described in the detailed description of the disclosure. However, this does not limit the disclosure within specific embodiments and it should be understood that the disclosure covers all the modifications, equivalents, and replacements within the idea and technical scope of the disclosure.

[0048] Parts that are irrelevant to the description may be omitted to clearly describe the disclosure, and the same elements will be designated by the same reference numerals throughout the specification.

[0049] The thicknesses of some layers and areas may be exaggerated for convenience of explanation. In the drawings, the thickness of layers, films, panels, regions, etc., may be exaggerated for clarity. The thicknesses of some layers and areas are exaggerated for convenience of explanation.

[0050] It will be understood that when an element such as a layer, film, region, or substrate is referred to as being “on,” “connected to,” or “coupled to” another element, it can be directly on, or connected or coupled to the another element or intervening elements may also be present. In contrast, when an element is referred to as being “directly on” another element, there are no intervening elements present. The word “on” or “above” means positioned on or below the object portion and does not necessarily mean positioned on the upper side of the object portion based on a

gravitational direction.

[0051] Unless explicitly described to the contrary, the word “comprise” or “include” and variations such as “comprises” “comprising,” or “including” will be understood to imply the inclusion of stated elements but not the exclusion of any other elements.

[0052] The phrase “in a plan view” means viewing an object portion from the top, and the phrase “in a cross-sectional view” means viewing a cross-section of which the object portion is vertically cut from the side.

[0053] As used herein, the term “and/or” includes any and all combinations of one or more of the associated listed items. For example, “A and/or B” may be understood to mean “A, B, or A and B.”

[0054] It will be understood that, although the terms “first,” “second,” etc. may be used herein to describe various elements, components, regions, layers and/or sections, these elements, components, regions, layers and/or sections should not be limited by these terms. These terms are only used to distinguish one element, component, region, layer or section from another region, layer or section. Thus, a first element, component, region, layer or section discussed below could be termed a second element, component, region, layer or section without departing from the scope of the claims. The singular forms, “a,” “an” and “the” are intended to include the plural forms as well, unless referred to the contrary.

[0055] Unless otherwise defined or implied herein, all terms (including technical and scientific terms) used have the same meaning as commonly understood by those skilled in the art to which this disclosure pertains. It will be further understood that terms, such as those defined in commonly used dictionaries, should be interpreted as having a meaning that is consistent with their meaning in the context of the relevant art and should not be interpreted in an ideal or excessively formal sense unless clearly defined in the specification.

[0056] In the specification and the claims, the phrase “at least one of” is intended to include the meaning of “at least one selected from the group of” for the purpose of its meaning and interpretation. For example, “at least one of A and B” may be understood to mean “A, B, or A and B.”

[0057] Hereinafter, a display device according to an embodiment of the disclosure will be explained in detail with reference to the accompanying drawings.

[0058] A pixel PX of a display device according to an embodiment will be described with reference to FIG. 1.

[0059] FIG. 1 shows a schematic circuit diagram of a display device according to an embodiment.

[0060] As shown in FIG. 1, the pixel PX of the display device includes multiple transistors T1, T2, T3, T4, T5, T6, and T7, electrically connected to wires 127, 128, 151, 152, 153, 154, 155, 171, 172, and 741, a storage capacitor Cst, a boost capacitor Cbt, and a light emitting diode LED.

[0061] The wires include a first initialization voltage line 127, a second initialization voltage line 128, a first scan line 151, a second scan line 152, an initialization control line 153, a bypass control line 154, an emission control line 155, a data line 171, a driving voltage line 172, and a common voltage line 741.

[0062] The first scan line 151 is electrically connected to a gate driver (not shown) to transmit a first scan signal GW to the second transistor T2. Voltages having opposite polarities may be applied to the first scan line 151 and second scan line 152, respectively, at the same time. For example, when a negative voltage is applied to the first scan line 151, a positive voltage may be applied to the second scan line 152. The second scan line 152 transmits a second scan signal GC to the third transistor T3.

[0063] The initialization control line 153 transmits an initialization control signal GI to the fourth transistor T4. The bypass control line 154 transmits a bypass signal GB to the seventh transistor T7. The bypass control line 154 may be electrically connected to a first scan line 151 at a previous stage (or of a previous pixel). The emission control line 155 transmits an emission control signal EM to the fifth transistor T5 and the sixth transistor T6.

[0064] The data line **171** transmits a data voltage DATA generated by a data driver (not shown). The luminance of light emitted by the light emitting diode (LED) may be dependent on the data voltage DATA applied to the pixel PX.

[0065] The driving voltage line **172** applies a driving voltage ELVDD. The first initialization voltage line **127** transmits a first initialization voltage VINT, and the second initialization voltage line **128** transmits a second initialization voltage AINT. The common voltage line **741** applies a common voltage ELVSS to a cathode of the light emitting diode LED. In an embodiment, constant voltages may be applied to the driving voltage line **172**, the first and second initialization voltage lines **127** and **128**, and the common voltage line **741**.

[0066] A configuration and a connection relationship of transistors will now be described in detail.

[0067] The driving transistor T1 may have p-type transistor characteristics and may include a polycrystalline semiconductor. The driving transistor T1 controls a current provided to an anode of the light emitting diode LED according to the data voltage DATA applied to the gate electrode of the driving transistor T1. Brightness of the light emitting diode LED is controlled by the driving current provided to the anode of the light emitting diode LED, so luminance of the light emitting diode LED may be controlled according to the data voltage DATA applied to the pixel PX. For this purpose, a first electrode of the driving transistor T1 is disposed to receive a driving voltage ELVDD through the fifth transistor T5 and is electrically connected to the driving voltage line **172**. The first electrode of the driving transistor T1 is electrically connected to a second electrode of the second transistor T2 to receive the data voltage DATA. A second electrode of the driving transistor T1 is disposed to provide a current to the light emitting diode LED through the sixth transistor T6, and is electrically connected to the anode of the light emitting diode LED. The second electrode of the driving transistor T1 transmits the data voltage DATA applied to the first electrode to the third transistor T3. A gate electrode of the driving transistor T1 is electrically connected to an electrode (hereinafter, "second storage electrode") of the storage capacitor Cst. The voltage at the gate electrode of the driving transistor T1 changes according to a voltage stored in the storage capacitor Cst, and a driving current output by the driving transistor T1 accordingly changes. The storage capacitor Cst also maintains the voltage at the gate electrode of the driving transistor T1 for a frame.

[0068] The second transistor T2 may have p-type transistor characteristics and may include a polycrystalline semiconductor. The second transistor T2 receives the data voltage DATA into the pixel PX. A gate electrode of the second transistor T2 is electrically connected to the first scan line **151** and an electrode (hereinafter, "first boost electrode") of the boost capacitor Cbt. A first electrode of the second transistor T2 is electrically connected to the data line **171**. A second electrode of the second transistor T2 is electrically connected to the first electrode of the driving transistor T1. In case that the second transistor T2 is turned on by a negative voltage of the first scan signal GW transmitted through the first scan line **151**, the data voltage DATA transmitted through the data line **171** is transmitted to the first electrode of the driving transistor T1.

[0069] The third transistor T3 may have n-type transistor characteristics and may include an oxide semiconductor. The third transistor T3 electrically connects the second electrode and the gate electrode of the driving transistor T1 to each other. The third transistor T3 transmits the compensation voltage that is changed in case that the data voltage (DATA) passes through the driving transistor T1 to the second storage electrode of the storage capacitor Cst. A gate electrode of the third transistor T3 is electrically connected to the second scan line **152**, and the first electrode of the third transistor T3 is electrically connected to the second electrode of the driving transistor T1. A second electrode of the third transistor T3 is electrically connected to a second storage electrode of the storage capacitor Cst, a gate electrode of the driving transistor T1, and another electrode (hereinafter, the second boost electrode) of the boost capacitor Cbt. The third transistor T3 is turned on by a positive voltage of the second scan signal GC received through the second scan line **152** to electrically connect the gate electrode and the second electrode of the driving

transistor T1 to each other, and transmits the voltage applied to the gate electrode of the driving transistor T1 to the second storage electrode of the storage capacitor Cst to store the voltage in the storage capacitor Cst.

[0070] The fourth transistor T4 may have n-type transistor characteristics and may include an oxide semiconductor. The fourth transistor T4 initializes the gate electrode of the driving transistor T1 and the second storage electrode of the storage capacitor Cst. A gate electrode of the fourth transistor T4 is electrically connected to the initialization control line 153, and a first electrode of the fourth transistor T4 is electrically connected to the first initialization voltage line 127. A second electrode of the fourth transistor T4 is electrically connected to the second electrode of the third transistor T3, the second storage electrode of the storage capacitor Cst, the gate electrode of the driving transistor T1, and the second boost electrode of the boost capacitor Cbt. The fourth transistor T4 is turned on by a positive voltage of the initialization control signal GI received through the initialization control line 153, and in this instance, transmits the first initialization voltage VINT to the gate electrode of the driving transistor T1 and the second storage electrode of the storage capacitor Cst. Accordingly, the voltage at the gate electrode of the driving transistor T1 and the storage capacitor Cst are initialized.

[0071] The fifth transistor T5 may be a p-type transistor and may include a polycrystalline semiconductor. The fifth transistor T5 transmits the driving voltage ELVDD to the driving transistor T1. A gate electrode of the fifth transistor T5 is electrically connected to the emission control line 155, a first electrode of the fifth transistor T5 is electrically connected to the driving voltage line 172, and a second electrode of the fifth transistor T5 is electrically connected to the first electrode of the driving transistor T1.

[0072] The sixth transistor T6 may be a p-type transistor and may include a polycrystalline semiconductor. The sixth transistor T6 transmits the driving current provided by the driving transistor T1 to the light emitting diode LED. A gate electrode of the sixth transistor T6 is electrically connected to the emission control line 155, a first electrode of the sixth transistor T6 is electrically connected to the second electrode of the driving transistor T1, and a second electrode of the sixth transistor T6 is electrically connected to the anode of the light emitting diode LED.

[0073] The seventh transistor T7 may be a p-type transistor and may include a polycrystalline semiconductor. The seventh transistor T7 initializes the anode of the light emitting diode LED. A gate electrode of the seventh transistor T7 is electrically connected to the bypass control line 154; a first electrode of the seventh transistor T7 is electrically connected to the anode of the light emitting diode LED; and a second electrode of the seventh transistor T7 is electrically connected to the second initialization voltage line 128. In case that the seventh transistor T7 is turned on by a negative voltage of the bypass signal GB, the second initialization voltage AINT is applied to the anode of the light emitting diode LED to initialize the light emitting diode LED.

[0074] In an embodiment, pixel PX includes seven transistors, a storage capacitor, and a boost capacitor, but the embodiments are not limited thereto. The number and types of transistors and capacitors, and their arrangements may be modified in various ways.

[0075] In an embodiment, the driving transistor T1 may include a polycrystalline semiconductor. The third transistor T3 and the fourth transistor T4 may include oxide semiconductors. The second transistor T2, the fifth transistor T5, the sixth transistor T6, and the seventh transistor T7 may include polycrystalline semiconductors. However, at least one of the second transistor T2, the fifth transistor T5, the sixth transistor T6, and the seventh transistor T7 may include an oxide semiconductor. The third transistor T3 and the fourth transistor T4 include different semiconductor materials from the driving transistor T1, so stability and reliability may be improved.

[0076] As described above, voltages having opposite polarities may be applied to the first scan line 151 and the second scan line 152. For example, a negative voltage is applied to the second scan line 152 in case that a positive voltage is applied to the first scan line 151, and a positive voltage is applied to the second scan line 152 in case that a negative voltage is applied to the first scan line

151. For example, the second scan signal GC applied to the second scan line **152** may be a signal inverted from the first scan signal GW applied to the first scan line **151**, and thereby the gate voltage of the driving transistor T1 may be reduced after data is provided. In contrast, the first scan signal GW increases the gate voltage of the driving transistor T1. Therefore, a black voltage may be reduced in case that the black voltage is provided. In an embodiment, the boost capacitor Cbt is disposed between the first scan line **151**, to which the first scan signal GW is applied, and the gate electrode of the driving transistor T1, thereby increasing the gate voltage of the driving transistor T1 and stably outputting the black voltage. As the boost capacitor Cbt has a greater capacitance, the gate voltage of the driving transistor T1 may be increased further. The gate voltage of the driving transistor T1 may be controlled by controlling the capacitance of the boost capacitor Cbt.

[0077] FIG. 2 to FIG. 10 are schematic plan views and cross-sectional views of a driving transistor T1, a third transistor T3, a first scan line **151**, a boost capacitor Cbt and other components of pixels according to the embodiment.

[0078] FIG. 2 shows a schematic plan view of a display device according to an embodiment, FIG. 3 shows a schematic cross-sectional view with respect to line III-III, and FIG. 4 shows a cross-sectional view with respect to line IV-IV of FIG. 2. FIG. 5 to FIG. 10 show sequential schematic plan views of manufacturing steps of a display device according to an embodiment. FIG. 2 and FIG. 5 to FIG. 10 show two adjacent pixels arranged symmetrically. However, the embodiments are not limited to this. For example, the two pixels may have a substantially same shape. For the sake of explanation, the pixel on a left side will be mainly described. Also, the seventh transistor T7 is electrically connected to the first scan line **151** at the previous stage (or of a previous pixel), which is therefore not illustrated, and a seventh transistor T7 at the next stage (or of a next pixel) is illustrated.

[0079] As shown in FIG. 2 to FIG. 10, a polycrystalline semiconductor including a channel **1132**, a first electrode **1131**, and a second electrode **1133** of the driving transistor T1 may be disposed on the substrate **110**. FIG. 5 illustrates a polycrystalline semiconductor which may further include channels, and first electrodes, and second electrodes of the second transistor T2, the fifth transistor T5, the sixth transistor T6, and the seventh transistor T7 in addition to the driving transistor T1.

[0080] The channel **1132** of the driving transistor T1 may have a bent shape in a plan view. However, the embodiments are not limited to such a shape, and the channel **1132** of the driving transistor T1 can be modified in various ways. For example, the channel **1132** of the driving transistor T1 may be bent in a different shape or may have a bar shape. The first electrode **1131** and the second electrode **1133** of the driving transistor T1 may be disposed on respective sides of the channel **1132** of the driving transistor T1. The first electrode **1131** of the driving transistor T1 may extend upward and downward in a plan view, a portion may extend downward to be electrically connected to the second electrode of the second transistor T2, and a portion may extend upward to be electrically connected to the second electrode of the fifth transistor T5. The second electrode **1133** of the driving transistor T1 may extend upward to be electrically connected to the first electrode of the sixth transistor T6 in a plan view.

[0081] A buffer layer **111** may be disposed between the substrate **110** and the polycrystalline semiconductor including the channel **1132**, the first electrode **1131**, and the second electrode **1133** of the driving transistor T1. The buffer layer **111** may have a single-layered or multi-layered structure. The buffer layer **111** may include an organic insulating material or an inorganic insulating material.

[0082] A first gate insulating layer **141** may be disposed on the polycrystalline semiconductor including the channel **1132**, the first electrode **1131**, and the second electrode **1133** of the driving transistor T1. The first gate insulating layer **141** may include a silicon nitride or a silicon oxide.

[0083] A first gate conductor including the gate electrode **1151** of the driving transistor T1 may be disposed on the first gate insulating layer **141**. FIG. 6 illustrates a polycrystalline semiconductor and a first gate conductor. The first gate conductor may further include gate electrodes of the

second transistor T2, the fifth transistor T5, the sixth transistor T6, and the seventh transistor T7 in addition to the driving transistor T1.

[0084] The gate electrode **1151** of the driving transistor T1 may overlap the channel **1132** of the driving transistor T1. The channel **1132** of the driving transistor T1 is overlapped or covered by the gate electrode **1151** of the driving transistor T1.

[0085] The first gate conductor may further include a first scan line **151** and an emission control line **155**. The first scan line **151** and the emission control line **155** may substantially extend in a horizontal direction. The first scan line **151** may be electrically connected to the gate electrode of the second transistor T2 and the first boost electrode **151a**. The first scan line **151** may be integral with the gate electrode of the second transistor T2. The first scan line **151** may be integral with the first boost electrode **151a**. The first scan line **151** may be electrically connected to the gate electrode of the seventh transistor T7 positioned on the pixel at the next stage (or of the next pixel). For example, a bypass control line electrically connected to the seventh transistor T7 may be a first scan line **151** at the previous stage (or of the previous pixel). The gate electrode of the fifth transistor T5 and the gate electrode of the sixth transistor T6 may be electrically connected to the emission control line **155**.

[0086] After the first gate conductor including the gate electrode **1151** of the driving transistor T1 is formed, a doping process may be performed. A portion of the polycrystalline semiconductor overlapped by the first gate conductor may not be doped, and a portion of the polycrystalline semiconductor not overlapped by the first gate conductor may be doped to have characteristics identical to a conductor. In this instance, the doping process may be performed with a p-type dopant, and the driving transistor T1 including a polycrystalline semiconductor, the second transistor T2, the fifth transistor T5, the sixth transistor T6, and the seventh transistor T7 may have p-type transistor characteristics.

[0087] A second gate insulating layer **142** may be disposed on the first gate conductor including the gate electrode **1151** of the driving transistor T1 and the first gate insulating layer **141**. The second gate insulating layer **142** may include a silicon nitride or a silicon oxide.

[0088] A second gate conductor including a first storage electrode **1153** of the storage capacitor Cst, a light blocking layer **3155** of the third transistor T3, and a light blocking layer **4155** of the fourth transistor T4 may be disposed on the second gate insulating layer **142**. FIG. 7 illustrates a polycrystalline semiconductor, a first gate conductor, and a second gate conductor.

[0089] The first storage electrode **1153** overlaps the gate electrode **1151** of the driving transistor T1 to form a storage capacitor Cst (refer to, e.g., FIG. 3). An opening **1152** is formed in the first storage electrode **1153** of the storage capacitor Cst. The opening **1152** of the first storage electrode **1153** of the storage capacitor Cst may overlap the gate electrode **1151** of the driving transistor T1. The light blocking layer **3155** of the third transistor T3 may overlap a channel **3137** of the third transistor T3 and the gate electrode **3151**. The light blocking layer **4155** of the fourth transistor T4 may overlap the channel **4137** of the fourth transistor T4 and the gate electrode **4151**.

[0090] The second gate conductor may further include a lower second scan line **152a**, a lower initialization control line **153a**, and a first initialization voltage line **127**. The lower second scan line **152a**, the lower initialization control line **153a**, and the first initialization voltage line **127** may substantially extend in the horizontal direction. The lower second scan line **152a** may be electrically connected to the light blocking layer **3155** of the third transistor T3. The lower second scan line **152a** may be integral with the light blocking layer **3155** of the third transistor T3. The lower initialization control line **153a** may be electrically connected to the light blocking layer **4155** of the fourth transistor T4. The lower initialization control line **153a** may be integral with the light blocking layer **4155** of the fourth transistor T4.

[0091] A first interlayer insulating layer **161** may be disposed on the second gate conductor including the first storage electrode **1153** of the storage capacitor Cst, the light blocking layer **3155** of the third transistor T3, and the light blocking layer **4155** of the fourth transistor T4. The first

interlayer insulating layer **161** may include a silicon nitride or a silicon oxide.

[0092] An oxide semiconductor including the channel **3137**, the first electrode **3136**, and the second electrode **3138** of the third transistor **T3**, and the channel **4137**, the first electrode **4136**, and the second electrode **4138** of the fourth transistor **T4**, may be disposed on the first interlayer insulating layer **161**. FIG. **8** illustrates a polycrystalline semiconductor, a first gate conductor, a second gate conductor, and an oxide semiconductor.

[0093] The oxide semiconductor may include at least one of unary metal oxides such as an indium (In) based oxide, a tin (Sn) based oxide, or a zinc (Zn) based oxide; binary metal oxides such as an In—Zn based oxide, a Sn—Zn based oxide, an Al—Zn based oxide, a Zn—Mg based oxide, a Sn—Mg based oxide, an In—Mg based oxide, or an In—Ga based oxide; ternary metal oxides such as an In—Ga—Zn based oxide, an In—Al—Zn based oxide, an In—Sn—Zn based oxide, a Sn—Ga—Zn based oxide, an Al—Ga—Zn based oxide, a Sn—Al—Zn based oxide, an In—Hf—Zn based oxide, an In—La—Zn based oxide, an In—Ce—Zn based oxide, an In—Pr—Zn based oxide, an In—Nd—Zn based oxide, an In—Sm—Zn based oxide, an In—Eu—Zn based oxide, an In—Gd—Zn based oxide, an In—Tb—Zn based oxide, an In—Dy—Zn based oxide, an In—Ho—Zn based oxide, an In—Er—Zn based oxide, an In—Tm—Zn based oxide, an In—Yb—Zn based oxide, or an In—Lu—Zn based oxide; and quaternary metal oxides such as an In—Sn—Ga—Zn based oxide, an In—Hf—Ga—Zn based oxide, an In—Al—Ga—Zn based oxide, an In—Sn—Al—Zn based oxide, an In—Sn—Hf—Zn based oxide, or an In—Hf—Al—Zn based oxide. For example, the oxide semiconductor may include an indium-gallium-zinc oxide (IGZO) from among the In—Ga—Zn—based oxide.

[0094] The channel **3137**, the first electrode **3136**, and the second electrode **3138** of the third transistor **T3** and the channel **4137**, the first electrode **4136**, and the second electrode **4138** of the fourth transistor **T4** may be electrically connected to each other and may be integral with each other. The first electrode **3136** and the second electrode **3138** of the third transistor **T3** may be positioned on respective sides of the channel **3137** of the third transistor **T3**. The first electrode **4136** and the second electrode **4138** of the fourth transistor **T4** may be disposed on respective sides of the channel **4137** of the fourth transistor **T4**. The second electrode **3138** of the third transistor **T3** may be electrically connected to the second electrode **4138** of the fourth transistor **T4**. The channel **3137** of the third transistor **T3** may overlap the light blocking layer **3155**. The channel **4137** of the fourth transistor **T4** may overlap the light blocking layer **4155**.

[0095] The oxide semiconductor may further include a second boost electrode **3138a**. The second boost electrode **3138a** may be electrically connected to the second electrode **3138** of the third transistor **T3**. The second boost electrode **3138a** may be integral with the second electrode **3138** of the third transistor **T3**. The second boost electrode **3138a** may be electrically connected to the second electrode **4138** of the fourth transistor **T4**. The second boost electrode **3138a** may be integral with the second electrode **4138** of the fourth transistor **T4**. The second boost electrode **3138a** may overlap the first boost electrode **151a**. The capacitance of the boost capacitor **Cbt** may be determined by an overlapping area of the first boost electrode **151a** and the second boost electrode **3138a** and the thicknesses of the second gate insulating layer **142** disposed between the first boost electrode **151a** and the second boost electrode **3138a** and the first interlayer insulating layer **161**.

[0096] A third gate insulating layer **143** may be disposed on the oxide semiconductor including the channel **3137**, the first electrode **3136**, and the second electrode **3138** of the third transistor **T3**, and the channel **4137**, the first electrode **4136**, and the second electrode **4138** of the fourth transistor **T4**. The third gate insulating layer **143** may be disposed on the oxide semiconductor and an entire side of the first interlayer insulating layer **161**. Therefore, the third gate insulating layer **143** may overlap upper sides and lateral sides of the channel **3137**, the first electrode **3136**, and the second electrode **3138** of the third transistor **T3** and the channel **4137**, the first electrode **4136**, and the second electrode **4138** of the fourth transistor **T4**. However, the embodiments are not limited

thereto, and the third gate insulating layer **143** may not be disposed on the oxide semiconductor and the entire side of the first interlayer insulating layer **161**. For example, the third gate insulating layer **143** may overlap the channel **3137** of the third transistor **T3** but may not overlap the first electrode **3136** and the second electrode **3138**. The third gate insulating layer **143** may overlap the channel **4137** of the fourth transistor **T4** but may not overlap the first electrode **4136** and the second electrode **4138**.

[0097] A third gate conductor including the gate electrode **3151** of the third transistor **T3** and the gate electrode **4151** of the fourth transistor **T4** may be disposed on the third gate insulating layer **143**. FIG. **9** illustrates a polycrystalline semiconductor, a first gate conductor, a second gate conductor, an oxide semiconductor, and a third gate conductor.

[0098] The gate electrode **3151** of the third transistor **T3** may overlap the channel **3137** of the third transistor **T3**. The gate electrode **3151** of the third transistor **T3** may overlap the light blocking layer **3155** of the third transistor **T3**.

[0099] The gate electrode **4151** of the fourth transistor **T4** may overlap the channel **4137** of the fourth transistor **T4**. The gate electrode **4151** of the fourth transistor **T4** may overlap the light blocking layer **4155** of the fourth transistor **T4**.

[0100] The third gate conductor may further include an upper second scan line **152b** and an upper initialization control line **153b**. The upper second scan line **152b** and the upper initialization control line **153b** may substantially extend in the horizontal direction. The upper second scan line **152b** forms the second scan line **152** together with a lower second scan line **152a**. The upper second scan line **152b** may be electrically connected to the gate electrode **3151** of the third transistor **T3**. The upper second scan line **152b** may be integral with the gate electrode **3151** of the third transistor **T3**. The upper initialization control line **153b** forms the initialization control line **153** together with the lower initialization control line **153a**. The upper initialization control line **153b** may be electrically connected to the gate electrode **4151** of the fourth transistor **T4**. The upper initialization control line **153b** may be integral with the gate electrode **4151** of the fourth transistor **T4**.

[0101] After the third gate conductor including the gate electrode **3151** of the third transistor **T3** and the gate electrode **4151** of the fourth transistor **T4** is formed, a doping process may be performed. A portion of the oxide semiconductor overlapped by the third gate conductor may not be doped, and a portion of the oxide semiconductor not overlapped by the third gate conductor may be doped to have same characteristics as a conductor. The channel **3137** of the third transistor **T3** may be disposed below the gate electrode **3151** to overlap the gate electrode **3151**. The first electrode **3136** and the second electrode **3138** of the third transistor **T3** may not overlap the gate electrode **3151**. The channel **4137** of the fourth transistor **T4** may be disposed below the gate electrode **4151** to overlap the gate electrode **4151**. The first electrode **4136** and the second electrode **4138** of the fourth transistor **T4** may not overlap the gate electrode **4151**. The second boost electrode **3138a** may not overlap the third gate conductor. The doping process of the oxide semiconductor may be performed with an n-type dopant, and thus the third transistor **T3** and the fourth transistor **T4** including oxide semiconductors may have n-type transistor characteristics.

[0102] A second interlayer insulating layer **162** may be disposed on the third gate conductor including the gate electrode **3151** of the third transistor **T3** and the gate electrode **4151** of the fourth transistor **T4**. The second interlayer insulating layer **162** may include a first opening **1165**, a second opening **1166**, a third opening **3165**, and a fourth opening **3166**.

[0103] The first opening **1165** may overlap at least part of the gate electrode **1151** of the driving transistor **T1**. The first opening **1165** may be further formed in the third gate insulating layer **143**, the first interlayer insulating layer **161**, and the second gate insulating layer **142**. The first opening **1165** may overlap the opening **1152** of the first storage electrode **1153**. The first opening **1165** may be disposed inside the opening **1152** of the first storage electrode **1153**.

[0104] The second opening **1166** may overlap at least part of the second electrode **3138** of the third transistor **T3**. The second opening **1166** may be further formed in the third gate insulating layer

143. The second opening **1166** may be disposed between the first scan line **151** and the second scan line **152** in a plan view. The second opening **1166** may not overlap the first scan line **151**. A side edge of the second opening **1166** may correspond to a side edge of the first scan line **151**. For example, the lower-side edge of the second opening **1166** may correspond to an upper-side edge of the first scan line **151**. However, the embodiments are not limited thereto, and the side edge of the second opening **1166** may not correspond to the side edge of the first scan line **151**. For example, the lower-side edge of the second opening **1166** may be spaced apart from the upper-side edge of the first scan line **151**, and the lower-side edge of the second opening **1166** may be disposed above the upper-side edge of the first scan line **151**. The second opening **1166** may not overlap the second scan line **152**. In this instance, the second opening **1166** may not overlap the upper second scan line **152b**. The second opening **1166** may not overlap the lower second scan line **152a**. The second opening **1166** may not overlap the boost capacitor Cbt. For example, the second opening **1166** may not overlap the overlapping portion of the first boost electrode **151a** and the second boost electrode **3138a**.

[0105] The third opening **3165** may overlap at least part of the second electrode **1133** of the driving transistor T1. The third opening **3165** may be further formed in the third gate insulating layer **143**, the first interlayer insulating layer **161**, the second gate insulating layer **142**, and the first gate insulating layer **141**. The fourth opening **3166** may overlap at least part of the first electrode **3136** of the third transistor T3. The fourth opening **3166** may be further formed in the third gate insulating layer **143**.

[0106] A first data conductor including a first connection electrode **1175** and a second connection electrode **3175** may be disposed on the second interlayer insulating layer **162**. FIG. **10** illustrates a polycrystalline semiconductor, a first gate conductor, a second gate conductor, an oxide semiconductor, a third gate conductor, and a first data conductor.

[0107] The first connection electrode **1175** may overlap the gate electrode **1151** of the driving transistor T1. The first connection electrode **1175** may be electrically connected to the gate electrode **1151** of the driving transistor T1 through the first opening **1165** and the opening **1152** of the first storage electrode **1153**. The first connection electrode **1175** may overlap the second electrode **3138** of the third transistor T3. The first connection electrode **1175** may be electrically connected to the second electrode **3138** of the third transistor T3 through the second opening **1166**. Therefore, the gate electrode **1151** of the driving transistor T1 may be electrically connected to the second electrode **3138** of the third transistor T3 by the first connection electrode **1175**. In this instance, the gate electrode **1151** of the driving transistor T1 may be electrically connected to the second boost electrode **3138a** and the second electrode **4138** of the fourth transistor T4 by the first connection electrode **1175**.

[0108] The first connection electrode **1175** may electrically contact the second electrode **3138** of the third transistor T3. A contact portion on which the first connection electrode **1175** electrically contacts the second electrode **3138** of the third transistor T3 may be disposed in the second opening **1166**. The second opening **1166** does not overlap the first scan line **151**, so the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 may not overlap the first scan line **151**. The first connection electrode **1175** may overlap the first scan line **151**. Part of the first connection electrode **1175** may overlap the first scan line **151**. However, the embodiments are not limited thereto. For example, the first connection electrode **1175** may not overlap the first scan line **151**. The second opening **1166** does not overlap the second scan line **152**, so at least part of the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 may not overlap the second scan line **152**. The contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 may not overlap the upper second scan line **152b**. The contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 may not overlap the lower second scan line **152a**. The first connection electrode **1175** may not overlap the second scan line **152a**. The second

opening **1166** does not overlap the boost capacitor Cbt, so the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 may not overlap the boost capacitor Cbt.

[0109] The second connection electrode **3175** may overlap the second electrode **1133** of the driving transistor T1. The second connection electrode **3175** may be electrically connected to the second electrode **1133** of the driving transistor T1 through the third opening **3165**. The second connection electrode **3175** may overlap the first electrode **3136** of the third transistor T3. The second connection electrode **3175** may be electrically connected to the first electrode **3136** of the third transistor T3 through the fourth opening **3166**. Therefore, the second connection electrode **3175** may electrically connect the second electrode **1133** of the driving transistor T1 and the first electrode **3136** of the third transistor T3 to each other.

[0110] The first data conductor may further include a second initialization voltage line **128**. The second initialization voltage line **128** may substantially extend in the horizontal direction.

[0111] A third interlayer insulating layer **180** may be disposed on the first data conductor including the first connection electrode **1175** and the second connection electrode **3175**.

[0112] A data line **171** and a driving voltage line **172** may be disposed on the third interlayer insulating layer **180**. The data line **171** and the driving voltage line **172** may substantially extend in the vertical direction. The data line **171** may be electrically connected to the second transistor T2. The driving voltage line **172** may be electrically connected to the fifth transistor T5. The driving voltage line **172** may be electrically connected to the first storage electrode **1153**.

[0113] Although not shown, a passivation layer may be disposed on the data line **171** and the driving voltage line **172**, and an anode may be disposed on the passivation layer. The anode may be electrically connected to the sixth transistor T6 and may receive an output current of the driving transistor T1. A partition wall may be disposed on the anode. An opening is formed in the partition wall, and the opening in the partition wall may overlap the anode. A light-emitting device layer may be disposed in the partition wall. A cathode may be disposed on the light-emitting device layer and in the partition wall. The anode, the light-emitting device layer, and the cathode may form a light emitting diode LED.

[0114] Regarding the display device according to an embodiment, the driving transistor T1 may include a polycrystalline semiconductor, and the third transistor T3 and the fourth transistor T4 may include oxide semiconductors. As described above, the third transistor T3 and the fourth transistor T4 include different semiconductor materials from the driving transistor T1, so the stability and reliability may be improved.

[0115] A compensation voltage transfer route CTR to a gate electrode of a driving transistor through a third transistor will now be described with reference to FIG. 11 together with FIG. 1 to FIG. 10.

[0116] FIG. 11 shows a schematic plan view of part of a display device in an embodiment. FIG. 11 shows some layers of a first scan line, a driving transistor, a third transistor, and a fourth transistor.

[0117] As shown in FIG. 11, the data voltage DATA applied through the second transistor T2 is transmitted to the third transistor T3 through the driving transistor T1. The third transistor T3 electrically connects the second electrode **1133** of the driving transistor T1 and the gate electrode **1151** of the driving transistor T1 to each other. The first electrode **3136** of the third transistor T3 electrically contacts the second electrode **1133** of the driving transistor T1, and the second electrode **3138** of the third transistor T3 electrically contacts the gate electrode **1151** of the driving transistor T1. The second electrode **3138** of the third transistor T3 is electrically connected to the gate electrode **1151** of the driving transistor T1 through the first connection electrode **1175**. The compensation voltage changed from the data voltage DATA by the third transistor T3 is transmitted to the gate electrode **1151** of the driving transistor T1 through the first connection electrode **1175**. The first electrode **3136**, the channel **3137**, and the second electrode **3138** of the third transistor T3 included in a compensation voltage transfer route CTR are made of oxide semiconductors. The

second electrode **3138** of the third transistor **T3** may overlap the first scan line **151**. The second electrode **3138** of the third transistor **T3** is integral with the second boost electrode **3138a**, the first scan line **151** is integral with the first boost electrode **151a**, and the first boost electrode **151a** overlaps the second boost electrode **3138a** to form a boost capacitor **Cbt**.

[0118] As described above, voltages with opposite polarities are applied at a same time to the first scan line **151** and the second scan line **152**. The first scan line **151** is electrically connected to the gate electrode of the second transistor **T2**, and the second scan line **152** is electrically connected to the gate electrode of the third transistor **T3**. The second transistor **T2** is a p-type transistor, and the third transistor **T3** is an n-type transistor. Therefore, in case that a negative voltage is applied to the first scan line **151** and a positive voltage is applied to the second scan line **152**, the second transistor **T2** and the third transistor **T3** are turned on.

[0119] A portion where the second electrode **3138** of the third transistor **T3** including an oxide semiconductor overlaps the first scan line **151** may be influenced by the negative voltage applied to the first scan line **151**. For example, the negative voltage may attract positive charges to the bottom surface of the second electrode **3138** of the third transistor **T3** that is near the first scan line **151**. Also, negative charges may gather on an upper side of the second electrode **3138** of the third transistor **T3** that is further away from the first scan line **151**. This may increase the resistance at a portion where the second electrode **3138** of the third transistor **T3** overlaps the first scan line **151**, and thus the voltage may not be smoothly transmitted.

[0120] In an embodiment, the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor **T3** may not overlap the first scan line **151**. Thus, the compensation voltage transfer route **CTR** may avoid the portion where the second electrode **3138** of the third transistor **T3** overlaps the first scan line **151**. Therefore, resistance is prevented from increasing in the compensation voltage transfer route **CTR**, the compensation voltage may be smoothly transmitted, and horizontal line defects may be reduced.

[0121] It has been described in the above that the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor **T3** does not overlap the first scan line **151**. However, the embodiments are not limited thereto. For example, the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor **T3** does not overlap the first scan line **151** and other wires for applying a negative voltage, so equivalent or similar effects may be obtained.

[0122] A display device according to a comparative example will now be described with reference to FIG. **12** and FIG. **13**.

[0123] FIG. **12** shows a schematic plan view of a display device according to a comparative example, and FIG. **13** shows a schematic cross-sectional view with respect to line XIII-XIII of FIG. **12**.

[0124] As shown in FIG. **12** and FIG. **13**, the display device according to a comparative example mostly has a same configuration as the above-described display device according to an exemplary embodiment except that the second opening **1166** overlaps the first scan line **151**.

[0125] Regarding the display device according to a comparative example, the entire second opening **1166** overlaps the first scan line **151**. Therefore, the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor **T3** overlaps the first scan line **151**. Therefore, the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor **T3** overlaps the boost capacitor **Cbt**.

[0126] Regarding the display device according to a comparative example, the compensation voltage transfer route passes through a portion where the second electrode **3138** of the third transistor **T3** overlaps the first scan line **151**. Hence, the resistance of the compensation voltage transfer route increases, and the compensation voltage is not smoothly transmitted, which may be seen as horizontal stains.

[0127] Regarding the display device according to an exemplary embodiment, the compensation

voltage transfer route avoids the portion where the second electrode **3138** of the third transistor T3 overlaps the first scan line **151**, so the compensation voltage may be smoothly transmitted compared to the display device according to a comparative example.

[0128] An embodiment will be described with reference to FIG. **14** to FIG. **16**.

[0129] The embodiments described in FIG. **14** to FIG. **16** are similar to the embodiments described with reference to FIG. **1** to FIG. **11**. In an embodiment, the contact portion of the first connection electrode and the second electrode of the third transistor partly overlaps the first scan line, and this feature is at least distinguishable from the above-described embodiment(s) and will now be described.

[0130] FIG. **14** shows a schematic plan view of a display device according to an embodiment, FIG. **15** shows a schematic cross-sectional view with respect to line XV-XV of FIG. **14**, and FIG. **16** shows a schematic plan view of part of a display device according to an embodiment.

[0131] As shown in FIG. **14** to FIG. **16**, the display device according to an embodiment includes multiple wires **127**, **128**, **151**, **152**, **153**, **154**, **155**, **171**, and **172**, multiple T1, T2, T3, T4, T5, T6, and T7 electrically connected to the wires, a storage capacitor Cst, a boost capacitor Cbt, and a light emitting diode LED (not shown).

[0132] The third transistor T3 includes a first electrode **3136** electrically connected to the first electrode **1131** of the driving transistor T1, a second electrode **3138** electrically connected to the first connection electrode **1175**, a channel **3137** disposed between the first electrode **3136** and the second electrode **3138**, and a gate electrode **3151** overlapping the channel **3137**.

[0133] A second interlayer insulating layer **162** may be disposed on the gate electrode **3151** of the third transistor T3, and the second interlayer insulating layer **162** may include a first opening **1165**, a second opening **1166**, a third opening **3165**, and a fourth opening **3166**.

[0134] The second opening **1166** may overlap at least part of the second electrode **3138** of the third transistor T3. The second opening **1166** may be further formed in the third gate insulating layer **143**. The second opening **1166** may be disposed between the first scan line **151** and the second scan line **152** in a plan view. At least part of the second opening **1166** may not overlap the first scan line **151**. Part of the second opening **1166** may overlap the first scan line **151**, and the remaining part of the second opening **1166** may not overlap the first scan line **151**. For example, a half of the second opening **1166** may overlap the first scan line **151**, and the other half of the second opening **1166** may not overlap the first scan line **151**. The second opening **1166** may not overlap the second scan line **152**. In this instance, the second opening **1166** may not overlap the upper second scan line **152b**. The second opening **1166** may not overlap the lower second scan line **152a**. At least part of the second opening **1166** may not overlap the boost capacitor Cbt. For example, at least part of the second opening **1166** may not overlap the overlapping portion of the first boost electrode **151a** and the second boost electrode **3138a**. Part of the second opening **1166** may overlap the boost capacitor Cbt, and the remaining part of the second opening **1166** may not overlap the boost capacitor Cbt.

[0135] The first connection electrode **1175** may be electrically connected the second electrode **3138** of the third transistor T3 through the second opening **1166**.

[0136] The first connection electrode **1175** may electrically contact the second electrode **3138** of the third transistor T3. The contact portion where the first connection electrode **1175** electrically contacts the second electrode **3138** of the third transistor T3 may be disposed in the second opening **1166**. At least part of the second opening **1166** does not overlap the first scan line **151**, so at least part of the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 may not overlap the first scan line **151**. Part of the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 may overlap the first scan line **151**, and the remaining part of the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 may not overlap the first scan line **151**. The first connection electrode **1175** may overlap the first scan line **151**. Part of the first connection electrode **1175** may overlap the first scan line **151**. The second opening **1166** does not

overlap the second scan line **152**, so at least part of the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor **T3** may not overlap the second scan line **152**. The contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor **T3** may not overlap the upper second scan line **152b**. The contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor **T3** may not overlap the lower second scan line **152a**. The first connection electrode **1175** may not overlap the second scan line **152a**. At least part of the second opening **1166** does not overlap the boost capacitor **Cbt**, so at least part of the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor **T3** may not overlap the boost capacitor **Cbt**. Part of the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor **T3** may overlap the boost capacitor **Cbt**, and the remaining part of the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor **T3** may not overlap the boost capacitor **Cbt**.

[0137] Regarding the display device according to an embodiment, at least part of the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor **T3** may not overlap the first scan line **151**. Thus, the compensation voltage transfer route **CTR** may avoid the portion where the second electrode **3138** of the third transistor **T3** overlaps the first scan line **151**. Therefore, the resistance of the compensation voltage transfer route **CTR** may be prevented from increasing, the compensation voltage may be smoothly transmitted, and the horizontal line defects may be reduced.

[0138] It has been described that at least part of the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor **T3** does not overlap the first scan line **151**, but the embodiments are not limited thereto. For example, at least part of the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor **T3** does not overlap the first scan line **151** and other wires for applying a negative voltage, so identical or similar effects may be obtained.

[0139] A display device according to an embodiment will now be described with reference to FIG. **17** to FIG. **19**.

[0140] The display device according to an embodiment described with reference to FIG. **17** to FIG. **19**, which will not be described, mostly corresponds to the display device according to an embodiment described with reference to FIG. **1** to FIG. **11**. In an embodiment, the first connection electrode does not overlap the first scan line, and at least this feature is distinguishable from the above-described embodiment(s) and will now be described.

[0141] FIG. **17** shows a schematic plan view of a display device according to an embodiment, FIG. **18** shows a schematic cross-sectional view with respect to line XVIII-XVIII of FIG. **17**, and FIG. **19** shows a schematic plan view of part of a display device according to an embodiment.

[0142] As shown in FIG. **17** to FIG. **19**, the display device according to an embodiment includes wires **127**, **128**, **151**, **152**, **153**, **154**, **155**, **171**, and **172**, transistors **T1**, **T2**, **T3**, **T4**, **T5**, **T6**, and **T7** electrically connected to the wires, a storage capacitor **Cst**, a boost capacitor **Cbt**, and a light emitting diode **LED** (not shown).

[0143] The third transistor **T3** includes a first electrode **3136** electrically connected to the first electrode **1131** of the driving transistor **T1**, a second electrode **3138** electrically connected to the first connection electrode **1175**, a channel **3137** disposed between the first electrode **3136** and the second electrode **3138**, and a gate electrode **3151** overlapping the channel **3137**.

[0144] A second interlayer insulating layer **162** is disposed on the gate electrode **3151** of the third transistor **T3**, and the second interlayer insulating layer **162** may include a first opening **1165**, a second opening **1166**, a third opening **3165**, and a fourth opening **3166**.

[0145] The second opening **1166** may overlap at least part of the second electrode **3138** of the third transistor **T3**. The second opening **1166** may be further included in the third gate insulating layer **143**. The second opening **1166** may be disposed between the first scan line **151** and the second scan

line **152** in a plan view. The second opening **1166** may not overlap the first scan line **151**. The second opening **1166** may be separated from the first scan line **151**. The second opening **1166** may not overlap the second scan line **152**. In this instance, the second opening **1166** may not overlap the upper second scan line **152b**. The second opening **1166** may not overlap the lower second scan line **152a**. The second opening **1166** may not overlap the boost capacitor Cbt. For example, the second opening **1166** may not overlap the overlapping portion of the first boost electrode **151a** and the second boost electrode **3138a**. The second opening **1166** may be separated from the boost capacitor Cbt.

[0146] The first connection electrode **1175** may be electrically connected the second electrode **3138** of the third transistor T3 through the second opening **1166**.

[0147] The first connection electrode **1175** may electrically contact the second electrode **3138** of the third transistor T3. The contact portion where the first connection electrode **1175** electrically contacts the second electrode **3138** of the third transistor T3 may be disposed in the second opening **1166**. The second opening **1166** does not overlap the first scan line **151**, so the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 may not overlap the first scan line **151**. The first connection electrode **1175** may not overlap the first scan line **151**. The first connection electrode **1175** may be separated from the first scan line **151** with a predetermined interval therebetween. The second opening **1166** does not overlap the second scan line **152**, so at least part of the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 may not overlap the second scan line **152**. The contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 may not overlap the upper second scan line **152b**. The contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 may not overlap the lower second scan line **152a**. The first connection electrode **1175** may not overlap the second scan line **152a**. The second opening **1166** does not overlap the boost capacitor Cbt, so the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 may not overlap the boost capacitor Cbt.

[0148] Regarding the display device according to an embodiment, the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 may not overlap the first scan line **151**, and the first connection electrode **1175** may not overlap the first scan line **151**. Thus, the transfer route CTR of the compensation voltage may avoid the portion where the second electrode **3138** of the third transistor T3 overlaps the first scan line **151**. Therefore, the resistance of the compensation voltage transfer route CTR may be prevented from increasing, the compensation voltage may be smoothly transmitted, and the horizontal line defects may be reduced.

[0149] It has been described in the above that the contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 does not overlap the first scan line **151**, but the embodiments are not limited thereto. The contact portion of the first connection electrode **1175** and the second electrode **3138** of the third transistor T3 does not overlap the first scan line **151** and other wires for applying a negative voltage, so identical or similar effects may be obtained. Further, the first connection electrode **1175** may not overlap the first scan line **151** and other wires for applying a negative voltage.

[0150] While this disclosure has been described in connection with some embodiments, it is to be understood that the disclosure is not limited to the disclosed embodiments, but, on the contrary, is intended to cover various modifications and equivalent arrangements included within the spirit and scope of the appended claims.

Claims

1. A display device comprising: a light emitting diode electrically connected between a driving voltage line that applies a driving voltage and a common voltage line that applies a common voltage; a driving transistor electrically connected between the driving voltage line and the light emitting diode; a second transistor electrically connected between a first electrode of the driving transistor electrically connected to the driving voltage line and a data line that applies a data voltage; a first scan line electrically connected to a gate electrode of the second transistor; a third transistor electrically connected between a second electrode of the driving transistor electrically connected to the light emitting diode and a gate electrode of the driving transistor; a connection electrode that electrically connects the gate electrode of the driving transistor and the third transistor; and a contact portion where the connection electrode electrically contacts the third transistor, wherein at least a part of the contact portion does not overlap the first scan line, the driving transistor and the second transistor include polycrystalline semiconductors, and the third transistor includes an oxide semiconductor.
